Update on New 3D Layout

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- Bump pad layout details for new chips
  - RD53
  - FERMILAB

Università degli Studi di Trento

Joined meeting RD53 / sensor designers in CMS /ATLAS

chaired by Lino Demaria (Universita e INFN (IT))

Friday, 12 December 2014 from 16:00 to 18:22 (Europe/Zurich) at CERN (14-4-010)

Video Services Vidyo public room : Join_meeting_RD53___sensor_designers_in_CMS__ATLAS More Info | **Join Now!**

Friday, 12 December 2014

16:00 - 16:10 **Introduction** *10'*
- Speaker: Lino Demaria (Universita e INFN (IT))
- Material: **Slides**

16:10 - 16:25 **Feedback and perspectives from the chip side** *15'*
- Speaker: Mauricio Garcia-Sciveres (Lawrence Berkeley National Lab. (US))
- Material: **Slides**

16:25 - 16:35 **Feedback from HPK** *10'*
- Speaker: Yoshinobu Unno (High Energy Accelerator Research Organization (JP))
- Material: **Slides**

16:35 - 16:45 **Feedback from 3D CNM design** *10'*
- Speaker: Giulio Pellegrini (Universidad de Valencia (ES))
- Material: **Slides**

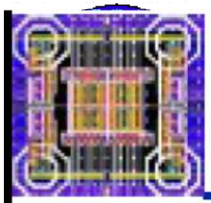
16:45 - 16:55 **Feedback from CIS and ADVACAM** *10'*
- Speaker: Anna Macchiolo (Max-Planck-Institut fuer Physik (Werner-Heisenberg-Institut) (D)
- Material: **Slides**

16:55 - 17:05 **Feedback from FBK 3D design** *10'*
- Speaker: Prof. Gian-Franco Dalla Betta (INFN and University of Trento)
- Material: **Slides**

17:05 - 17:15 **Feedback from 3D SINTEF design** *10'*
- Speakers: Angela Kok (SINTEF), Ozhan Koybasi (SINTEF)
- Material: **Slides**

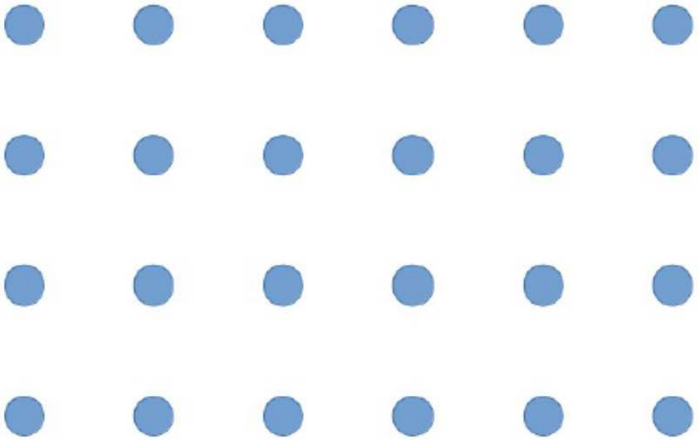
17:15 - 17:25 **Feedback from MICRON** *10'*
- Speaker: Gianluigi Casse (University of Liverpool (GB))

17:25 - 17:45 **Discussion** *20'*

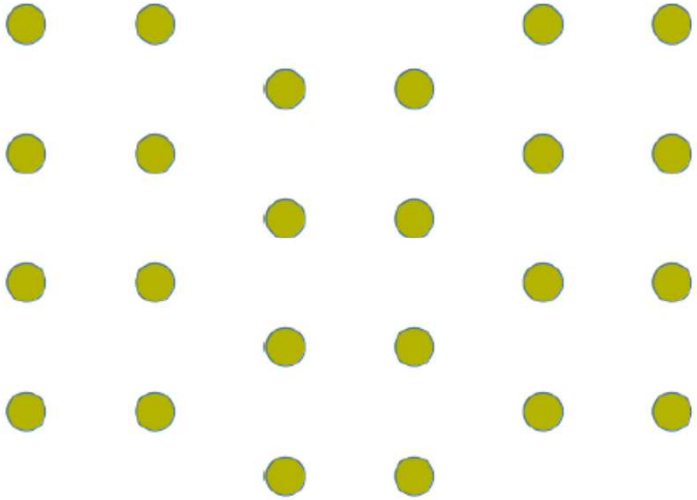


Two options for chip

1

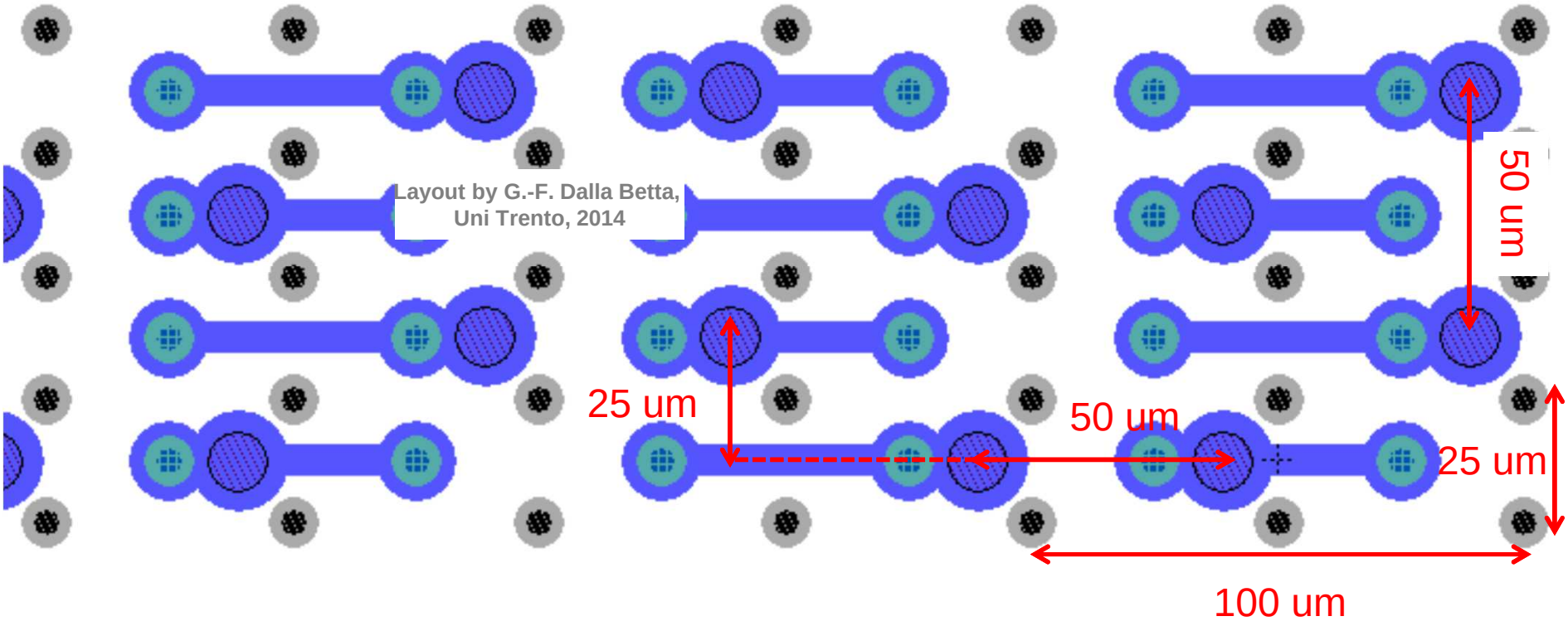


2



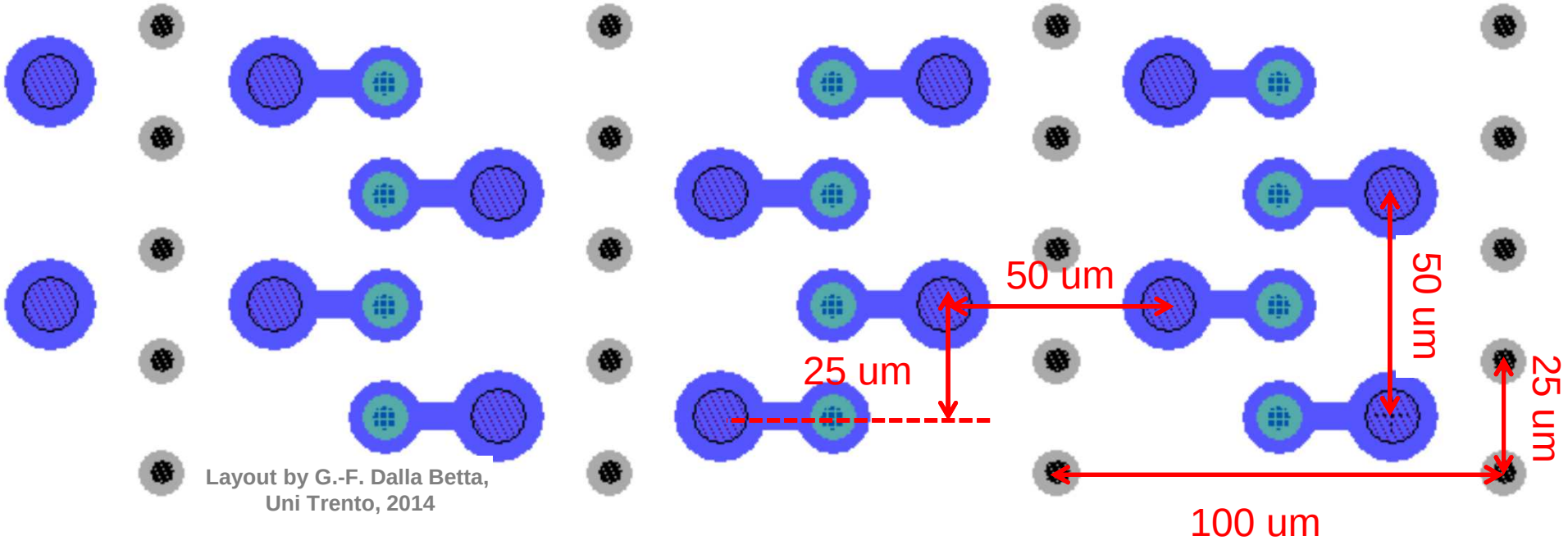
BUMP PADS RD53 (1): 25 x 100 (2E)

Only compatible with option 2



BUMP PADS RD53 (2): 25 x 100 (1E)

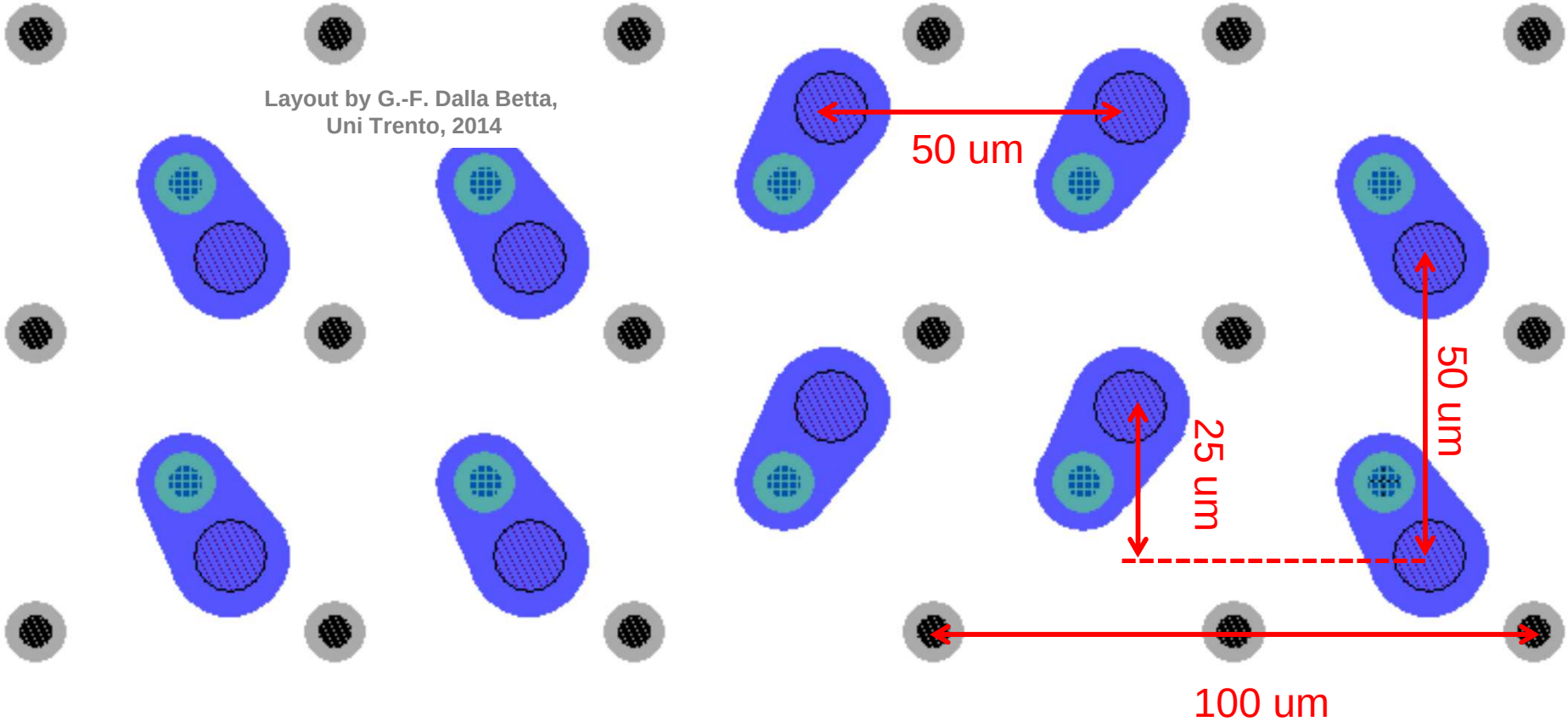
Compatible with options 1 and 2
(better with option 2 here shown)



Layout by G.-F. Dalla Betta,
Uni Trento, 2014

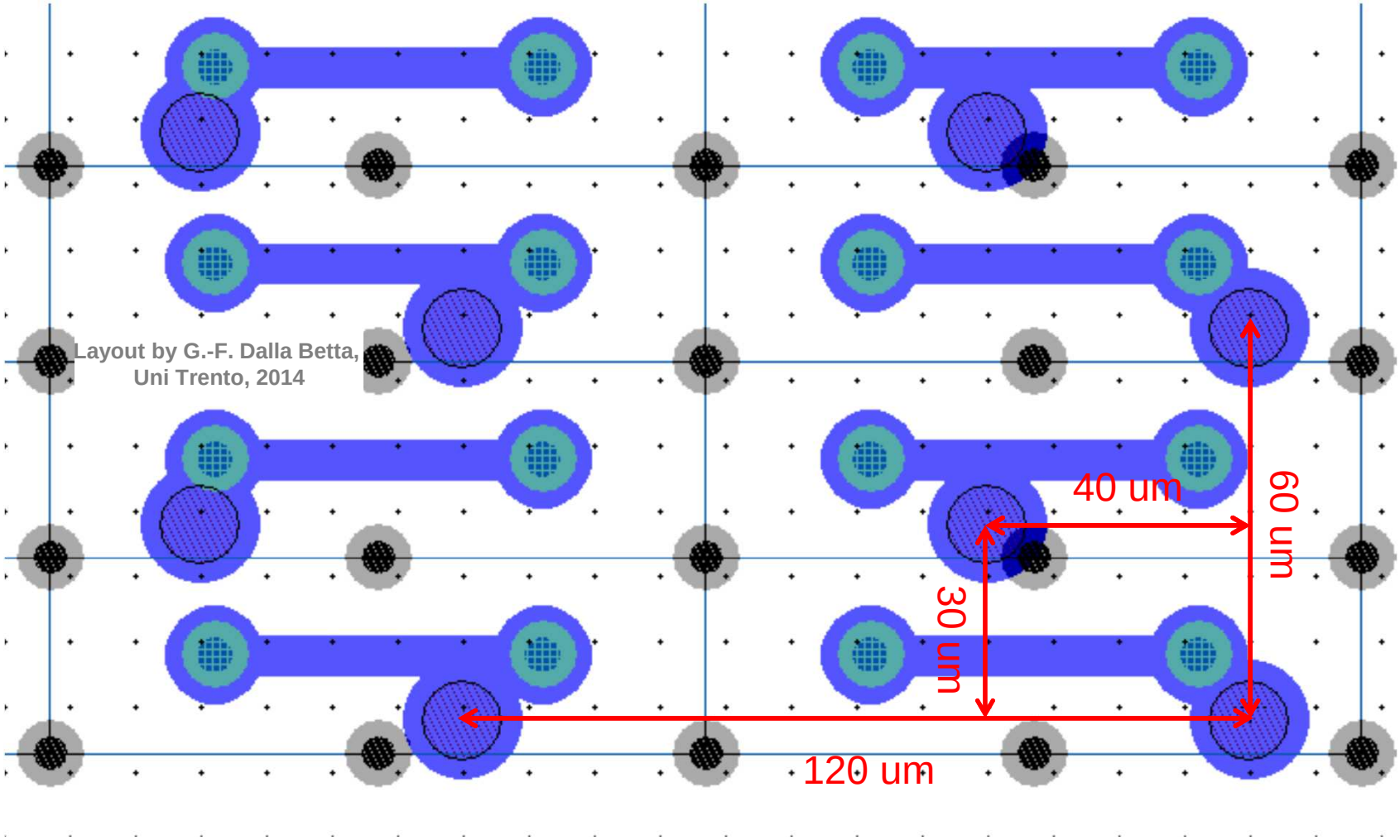
BUMP PADS RD53 (3): 50 x 50 (1E)

Compatible with options 1 and 2



FERMILAB CHIP (1): 100 x 30 (2E)

It could be compatible if bumps could sit on columns …



FERMILAB CHIP (2): 100 x 30 (1E)

Compatible, although not so nice